

### Thermal Characteristics

| Characteristic                                   | Symbol                            | Value       | Unit |
|--|-----------------------------------|-------------|------|
| Package Power Dissipation (Note 5)               | P <sub>D</sub>                    | 250         | mW   |
| Thermal Resistance, Junction to Ambient (Note 5) | $R_{	heta JA}$                    | 500         | °C/W |
| Operating and Storage Temperature Range          | T <sub>J</sub> , T <sub>STG</sub> | -65 to +150 | °C   |

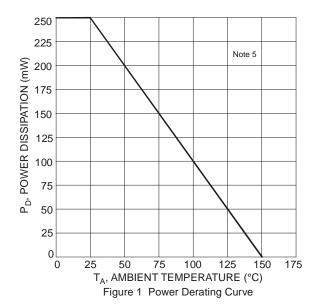
## Electrical Characteristics (@TA = +25°C unless otherwise specified)

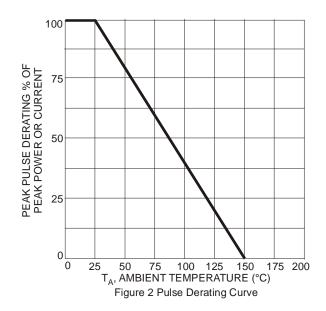
| Characteristic   | Symbol          | Min | Тур | Max  | Unit | Test Conditions                    |
|--|-----------------|-----|-----|------|------|------------------------------------|
| Reverse Working Voltage                                | $V_{RWM}$       |     |     | 5.5  | V    | _                                  |
| Reverse Current (Note 6)                               | I <sub>R</sub>  | _   | _   | 100  | nA   | V <sub>R</sub> = 5.0V              |
| Reverse Breakdown Voltage                              | $V_{BR}$        | 6.0 | _   | _    | V    | I <sub>R</sub> = 1mA               |
| Reverse Clamping Voltage, Positive Transients (Note 7) | V <sub>CL</sub> | _   | 10  | 12   | V    | $I_{PP} = 1A$ , $t_p = 8/20 \mu s$ |
| Dynamic Resistance                                     | $R_{DYN}$       | _   | 0.9 | _    | Ω    | $I_R = 1A$ , $t_p = 8/20 \mu s$    |
| Capacitance  | Ст              |     | 0.4 | 0.65 | pF   | $V_R = 2.5V, f = 1MHz$             |
|  |                 |     | 0.5 |      | pF   | $V_R = 0V$ , $f = 1MHz$            |

Notes:

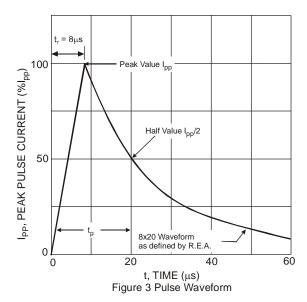
- 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

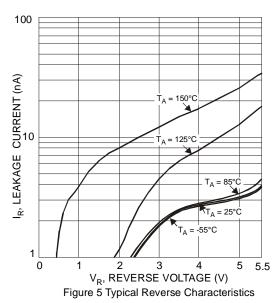
  6. Short duration pulse test used to minimize self-heating effect.
- 7. Clamping voltage value is based on an  $8x20\mu s$  peak pulse current ( $I_{pp}$ ) waveform. 8. Measured from any I/O to GND.
- 9. For information on the impact of Diodes' USB 2.0 compatible ESD protectors on signal integrity including eye diagram plots, please refer to AN77 at the following URL: http://www.diodes.com/destools/appnote\_dnote.html.

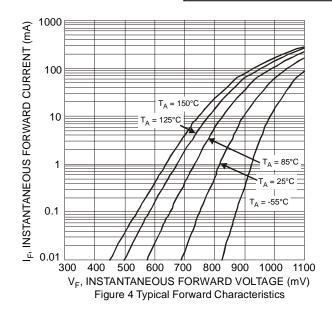












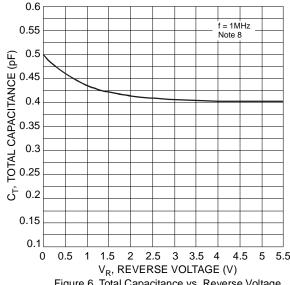
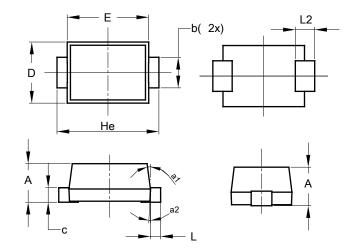


Figure 6 Total Capacitance vs. Reverse Voltage

# **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

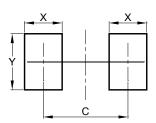


| SOD923               |           |      |      |  |  |  |
|----------------------|-----------|------|------|--|--|--|
| (0.3mm Lead Width)   |           |      |      |  |  |  |
| Dim                  | Min       | Max  | Тур  |  |  |  |
| Α                    | 0.34      | 0.40 | 0.37 |  |  |  |
| b                    | 0.25      | 0.35 | 0.30 |  |  |  |
| С                    | 0.05      | 0.15 | 0.10 |  |  |  |
| D                    | 0.55      | 0.65 | 0.60 |  |  |  |
| Е                    | 0.75      | 0.85 | 0.80 |  |  |  |
| He                   | 0.95      | 1.05 | 1.00 |  |  |  |
| L                    | 0.05      | 0.15 | 0.10 |  |  |  |
| L2                   | 0.190 REF |      |      |  |  |  |
| a1                   | 0°        | 8°   | 7°   |  |  |  |
| a2                   | 2°        | 4°   | 3°   |  |  |  |
| All Dimensions in mm |           |      |      |  |  |  |



## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



| Dimensions | Value<br>(in mm) |
|------------|------------------|
| С          | 0.900            |
| Х          | 0.400            |
| Y          | 0.600            |

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